



Description

The TDM303X, TDM304X, TDM306X and TDM308X series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-cross photo triac in a plastic SOP4 package.

With the robust coplanar double mold structure, TDM303X, TDM304X, TDM306X and TDM308X series provide the most stable isolation feature.

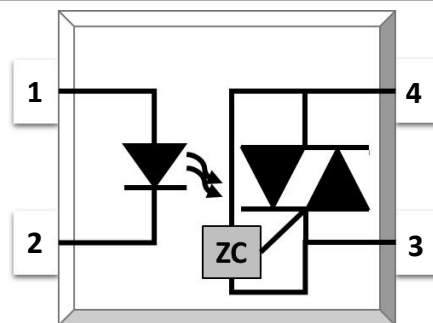
Features

- High isolation 3750 VRMS
 - DC input with zero-cross photo triac output
 - Operating temperature range - 40 °C to 100 °C
 - REACH compliance
 - Halogen free
 - MSL class 1
 - Regulatory Approvals
 - UL - UL1577
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC - GB4943.1, GB8898
 - cUL- CSA Component Acceptance
- Service Notice No. 5A

Applications

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

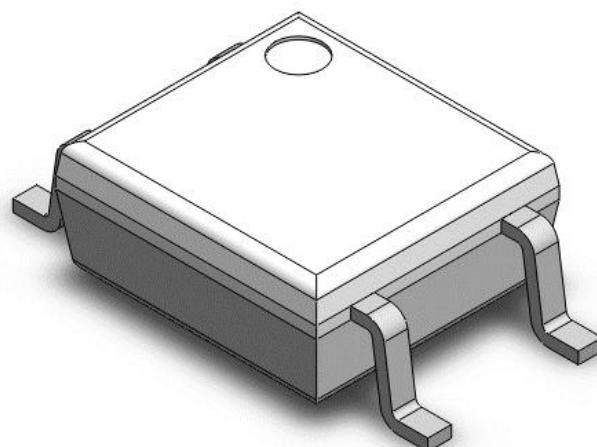
SCHEMATIC



PIN DEFINITION

1. Anode
2. Cathode
3. Terminal
4. Terminal

PACKAGE OUTLINE



**ABSOLUTE MAXIMUM RATINGS**

PARAMETER		SYMBOL	VALUE	UNIT	NOTE
INPUT					
Forward Current		I_F	60	mA	
Reverse Voltage		V_R	6	V	
Junction Temperature		T_j	125	°C	
Input Power Dissipation		P_I	100	mW	
OUTPUT					
Off-state Output Terminal Voltage	TDM303X	V_{DRM}	250	V	
	TDM304X		400		
	TDM306X		600		
	TDM308X		800		
Peak Repetitive Surge Current PW=100μs, 120pps		I_{TSM}	1	A	
On-State RMS Current		$I_{T(RMS)}$	100	mA	
Junction Temperature		T_j	125	°C	
Output Power Dissipation		P_O	300	mW	
COMMON					
Total Power Dissipation		P_{tot}	400	mW	
Isolation Voltage		V_{iso}	3750	V _{rms}	1
Operating Temperature		T_{opr}	-40~100	°C	
Storage Temperature		T_{stg}	-55~150	°C	
Soldering Temperature		T_{sol}	260	°C	2

Note 1. AC For 1 Minute, R.H. = 40 ~ 60%

Note 2. For 10 seconds


ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

PARAMETER		SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT								
Forward Voltage		V_F	-	1.24	1.4	V	$I_F=10\text{mA}$	
Reverse Current		I_R	-	-	10	μA	$V_R=6\text{V}$	
Input Capacitance		C_{in}	-	8.5	250	pF	$V=0, f=1\text{kHz}$	
OUTPUT								
Peak Off-state Current, Either Direction		I_{DRM}	-	-	500	nA	$V_{DRM}=\text{Rated } V_{DRM}$ $I_F=0$	3
Peak On-state Current, Either Direction		V_{TM}	-	1.42	2.5	V	$I_{TM}=100\text{mA}$	
Critical Rate of Rise of Off-state Voltage		dV/dt	1000	-	-	V/ μs	$V_{PEAK}=400\text{V},$ $I_F=0$	4
TRANSFER CHARACTERISTICS								
LED Trigger Current	TDM3031,TDM3041, TDM3061,TDM3081	I_{FT}	-	-	15	mA	Terminal Voltage = 3V $I_{TM}=100\text{mA}$	
	TDM3032,TDM3042, TDM3062,TDM3082		-	-	10			
	TDM3033,TDM3043, TDM3063,TDM3083		-	-	5			
Holding Current		I_H	-	450	-	μA		
Isolation Resistance		Riso	10^{12}	10^{14}	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance		C_{IO}	-	0.4	1	pF	$V=0, f=1\text{MHz}$	
ZERO-CROSSING CHARACTERISTICS								
Inhibit Voltage		V_{INH}	-	-	20	V	$I_F=\text{Rated } I_{FT}$	
Leakage in Inhibited State		I_{DRM2}	-	-	500	μA	$I_F=\text{Rated } I_{FT}$ $V_{DRM}=\text{Rated } V_{DRM}$	

Note3. Test voltage must be applied within dV/dt rating.

Note4. Refer to Fig.17 & Fig.18

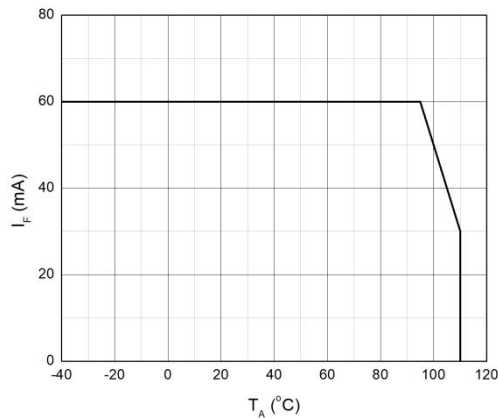
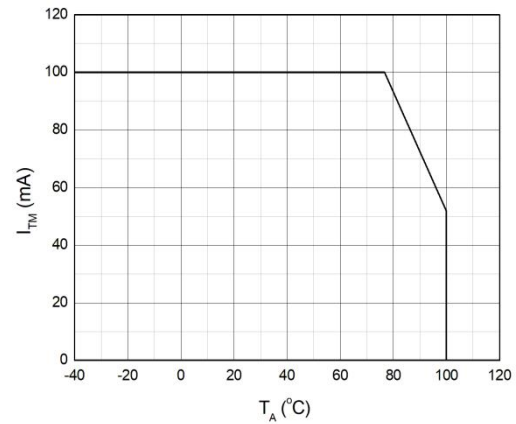
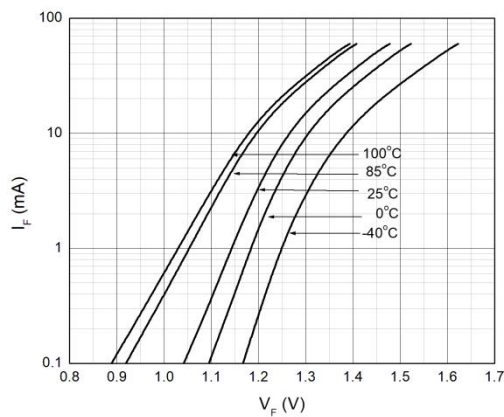
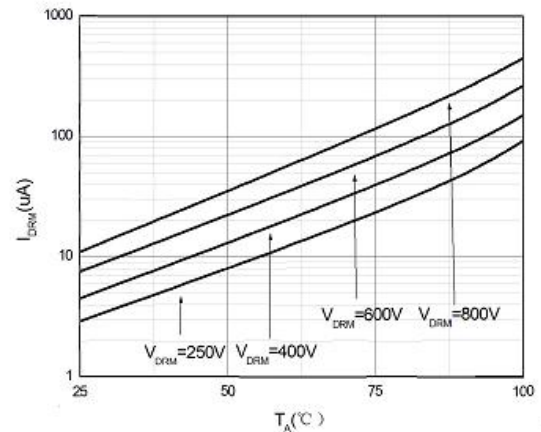
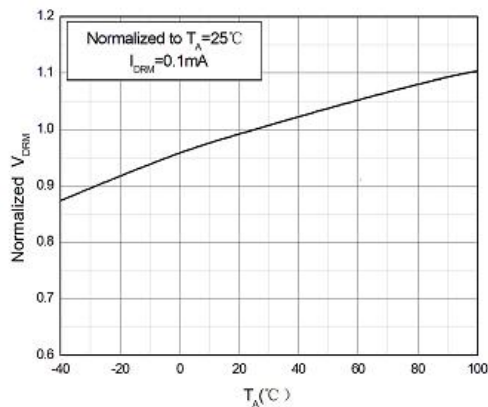
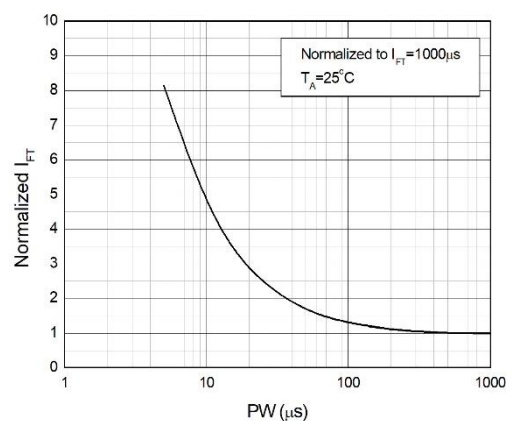
**CHARACTERISTIC CURVES****Fig.1 Forward Current vs. Ambient Temperature****Fig.2 On-state Terminal Current vs. Ambient Temperature****Fig.3 Forward Current vs. Forward Voltage****Fig.4 Off-state Terminal Current vs. Ambient Temperature****Fig.5 Normalized Off-state Terminal Voltage vs. Ambient Temperature****Fig.6 Normalized Trigger Current vs. LED Trigger Pulse Width****CHARACTERISTIC CURVES**



Fig.7 Normalized Trigger Current vs. Ambient Temperature

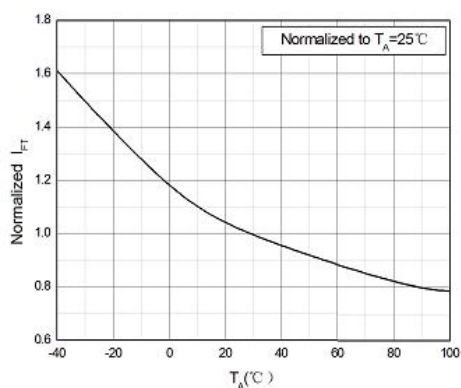


Fig.8 On-state Terminal Voltage vs. Ambient Temperature

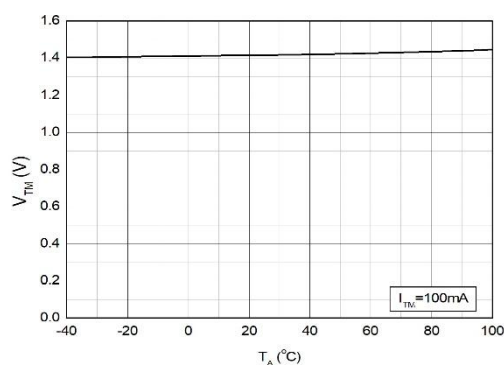


Fig.9 On-state Terminal Voltage vs. On-state Terminal Current

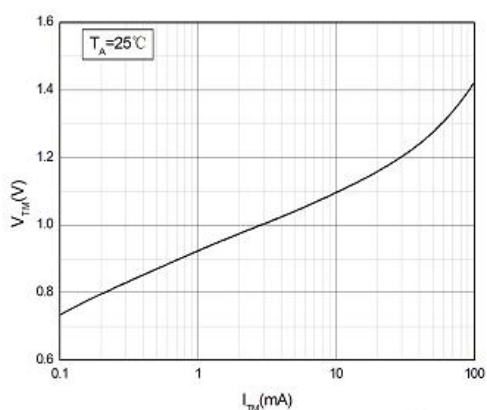


Fig.10 Holding Current vs. Ambient Temperature

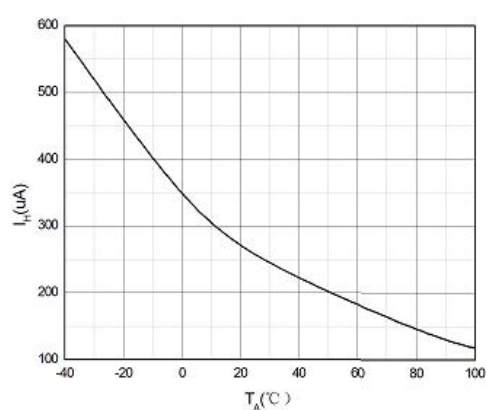


Fig.11 Normalized Inhibit Voltage vs. Ambient Temperature

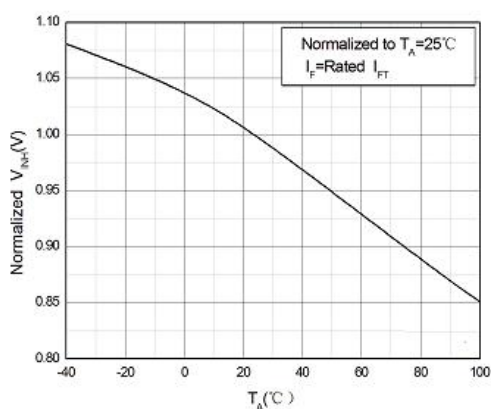
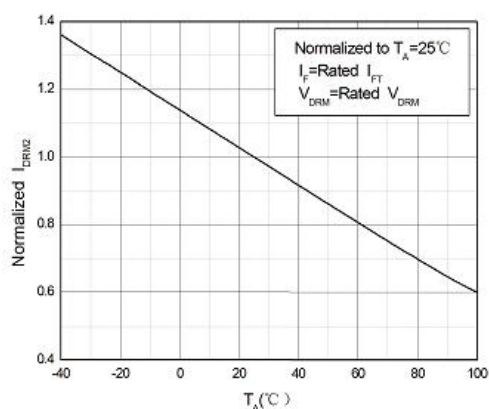


Fig.12 Normalized Leakage in Inhibit State vs. Ambient Temperature



CHARACTERISTIC CURVES

Fig.13 Turn On Time

Fig.14 Turn On Time



Fig.15 Forward Current

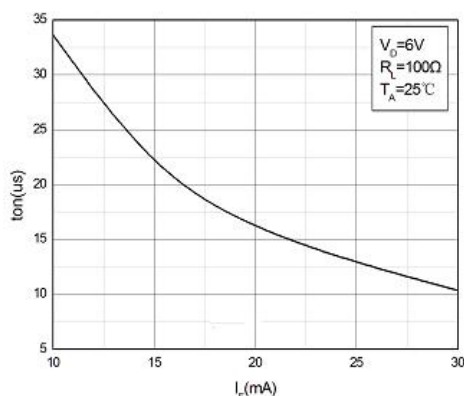
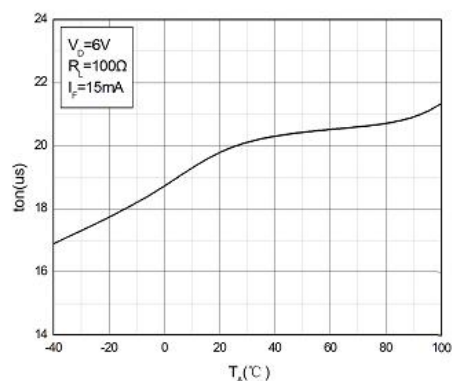


Fig.16 vs. Ambient Temperature



TEST CIRCUITS

Fig.15 Test Circuits of Turn On Time

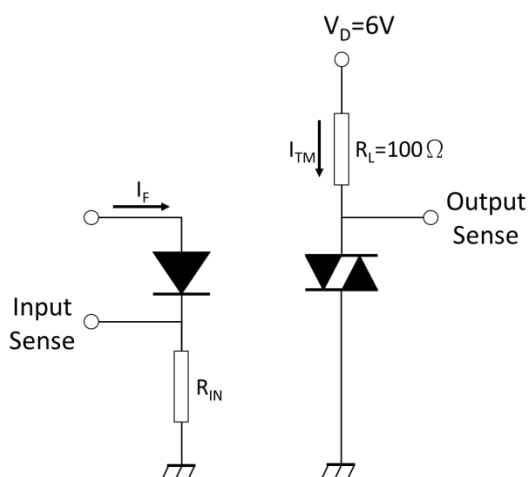


Fig.16 Waveforms of Turn On Time

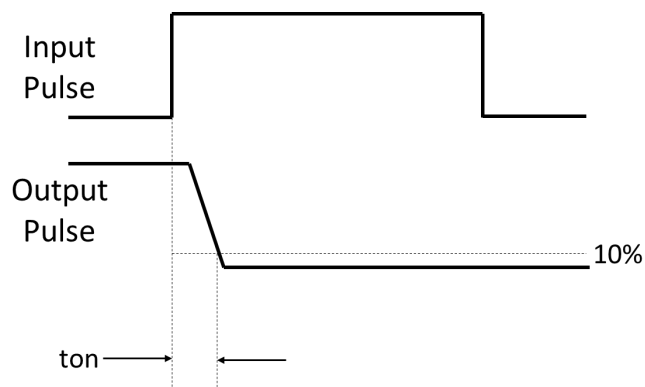


Fig.17 Test Circuits of dV/dt

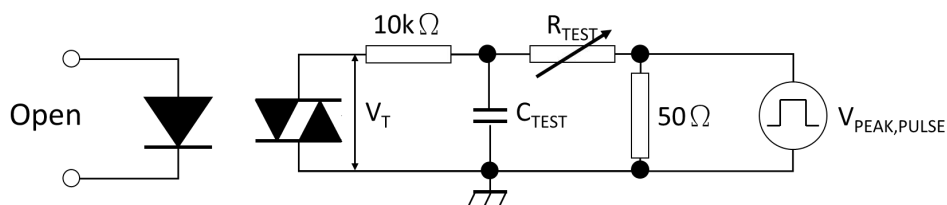
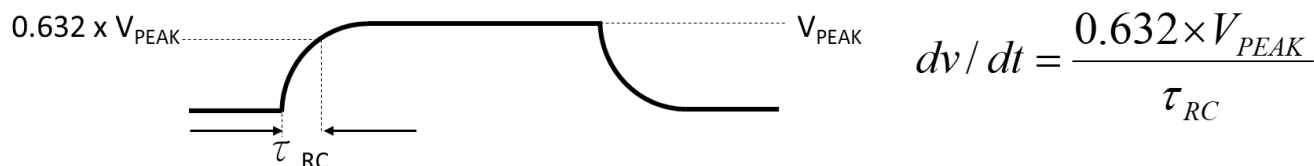
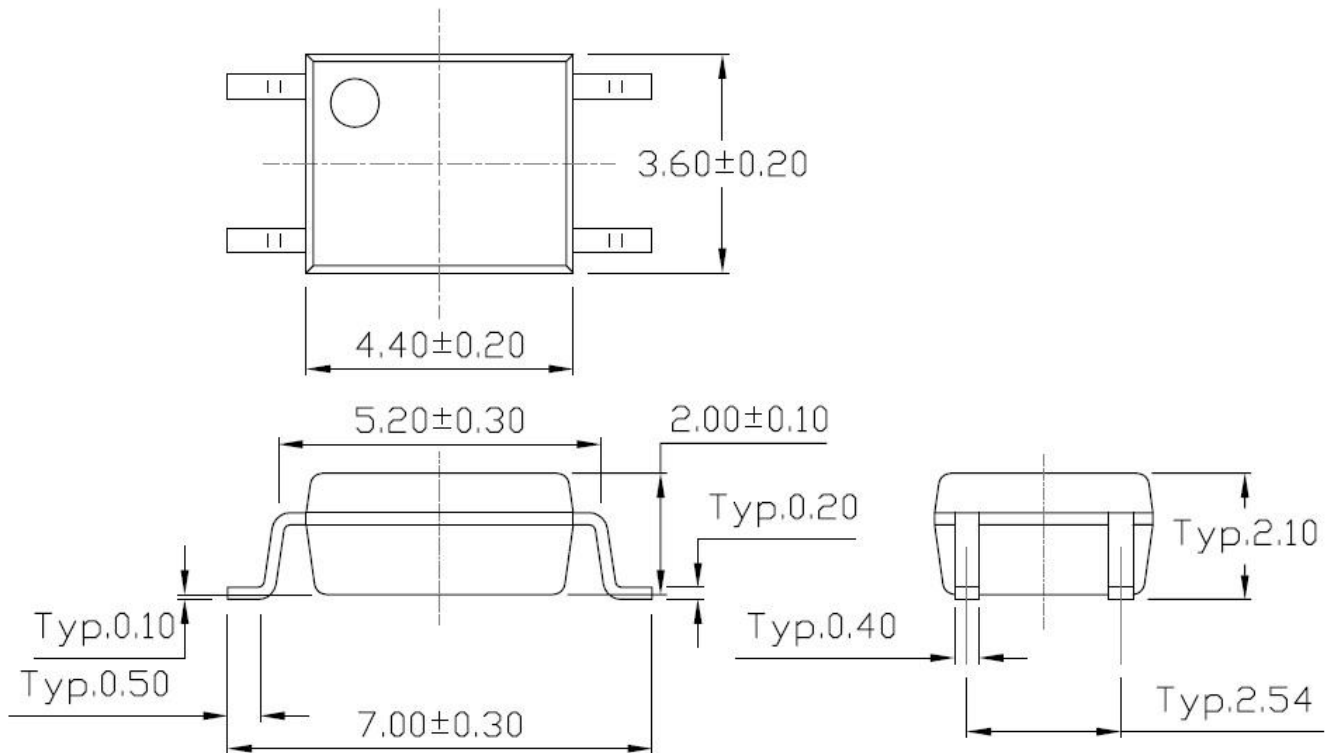


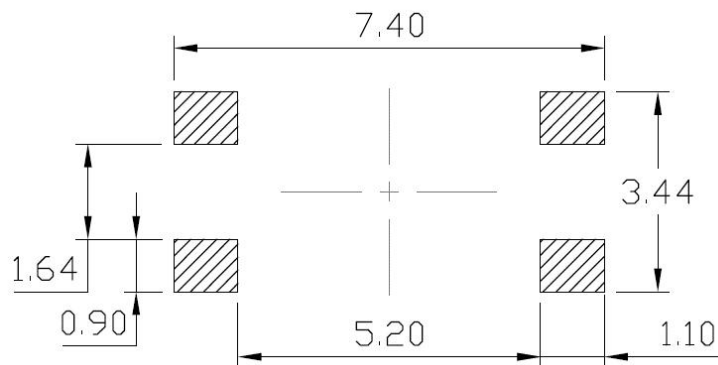
Fig.18 Waveforms of dV/dt



PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)



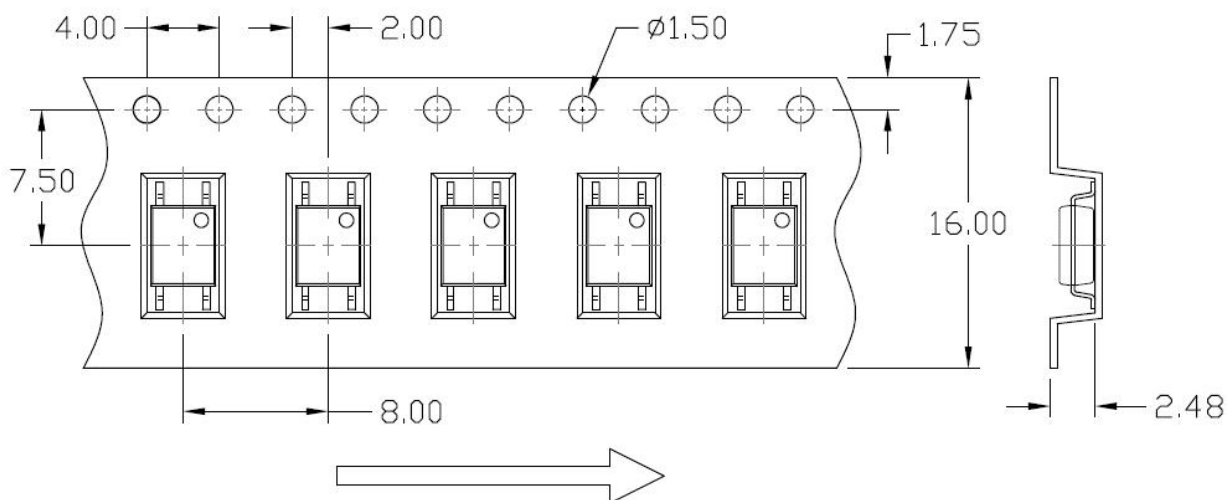
Recommended Solder Mask (Dimensions in mm unless otherwise stated)



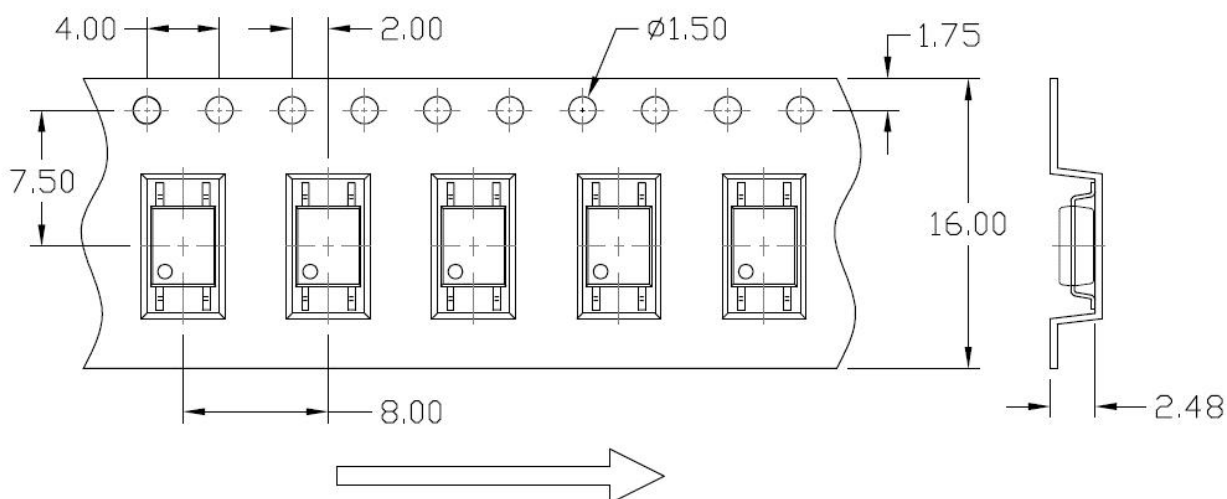


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



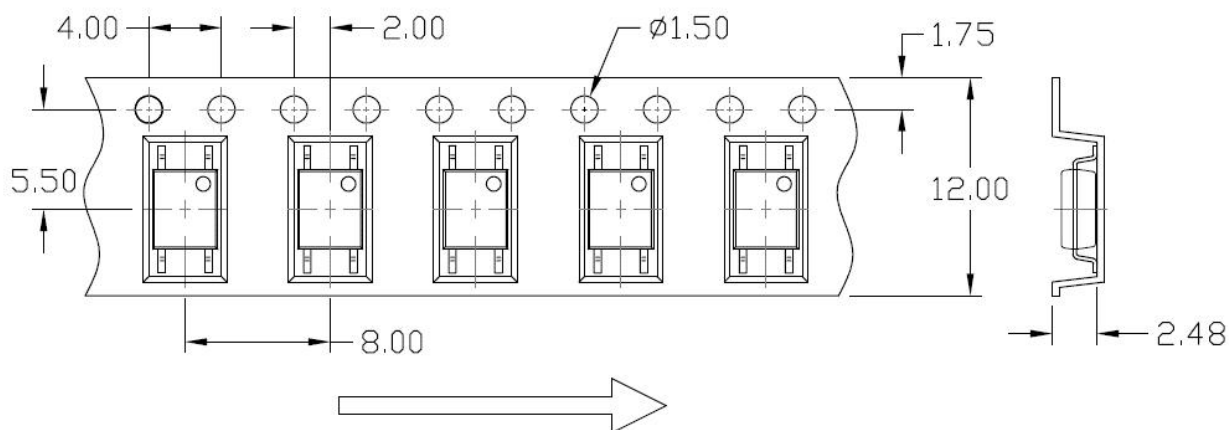
Option T2



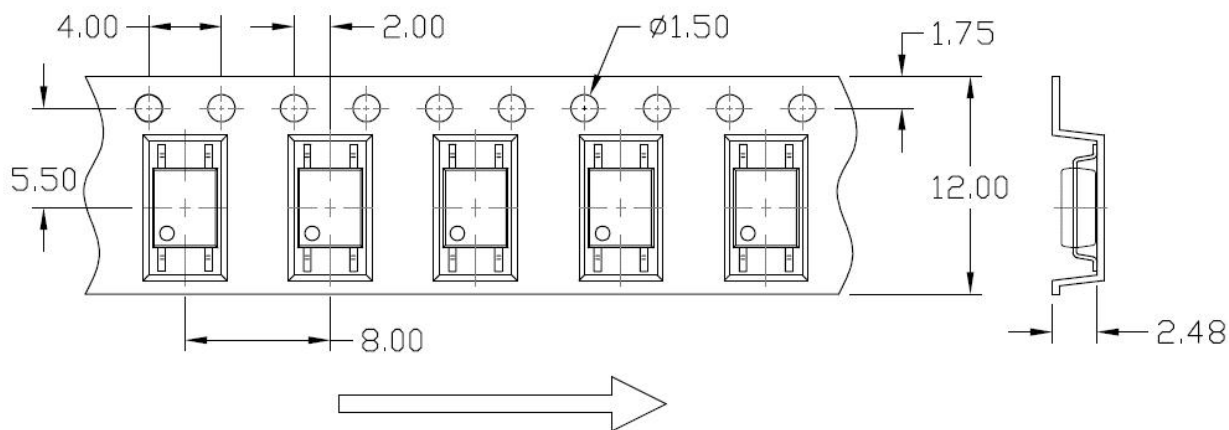


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T3



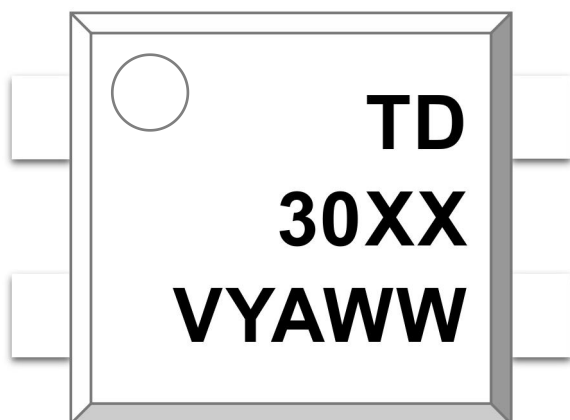
Option T4





ORDERING AND MARKING INFORMATION

MARKING INFORMATION



TD : Company Abbr.
30XX : Part Number & Rank
V : VDE Option
Y : Fiscal Year
A : Manufacturing Code
WW : Work Week

ORDERING INFORMATION

TDM30XX(Z)-GV

TD – Company Abbr.
 M – SOP Package
 30XX – Rank
 (31/32/33/41/42/43/61/62/63/81/82/83)
 Z – Tape and Reel Option (T1/T2)
 G – Green
 V – VDE Option (V or None)



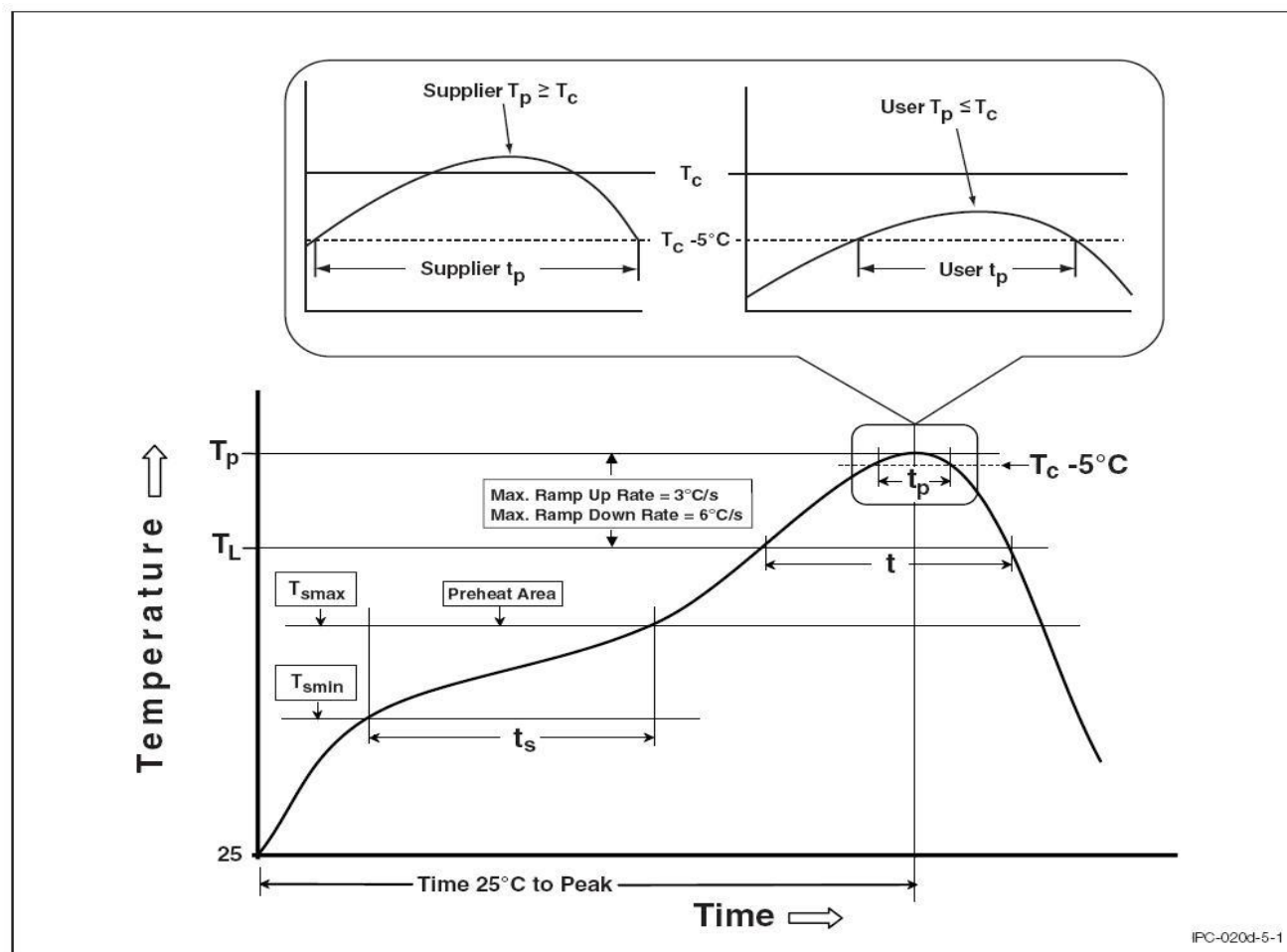
Packing Quantity

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Taping	3000Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	3000Units/Reel



REFLOW INFORMATION

REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150°C
Temperature Max. (T _{smax})	150	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



DISCLAIMER

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- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
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- The products shown in this publication are designed for the general use in electronic applications such as office automation, equipment, communications devices, audio/visual equipment, electrical application and instrumentation purpose, non-infringement and merchantability.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact LIGHTNING sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify LIGHTNING's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.